

**"VERSION WITH MARKINGS TO SHOW CHANGES MADE".**

1       Claim 26. An electronic package comprising:

2            a first flexible circuitized substrate having at least one conductive aperture therein

3            having an external surface;

4            a second flexible circuitized substrate having at least one conductive aperture

5            therein having an external surface, said first and second flexible circuitized substrates

6            aligned such that said at least one conductive aperture of said first flexible circuitized

7            substrate is substantially aligned with said at least one conductive aperture of said second

8            flexible circuitized substrate wherein said first and second flexible circuitized substrates are

9            comprised of a material selected from the group consisting of polyimide, polytetrafluoro-

10          ethylene, and epoxy glass cloth, said at least one conductive aperture of said first flexible

11          circuitized substrate and said at least one conductive aperture of said second flexible

12          circuitized substrate including a conductive metallic layer thereon selected from the group

13          consisting of copper, nickel, gold, chromium, solder and alloys thereof; and

14            at least one solder member including a first contact portion extending from said

15          external surface of said conductive aperture of said first flexible circuitized substrate and a

16          second contact portion extending substantially within both of said aligned conductive

17          apertures of said first and second flexible circuitized substrates to said external surface of

18          said conductive aperture of said second flexible circuitized substrate so as to substantially

19          form a solder dome thereon and secure said flexible circuitized substrates together [said

20          metallic material of said at least one conductive aperture of said first flexible circuitized

21          substrate and said at least one conductive aperture of said second flexible circuitized

22 substrate including a protective layer thereon, said protective layer selected from the  
23 group consisting of benzatriazole, chlorite, and immersion tin].

1           Claim 34. The electronic package of Claim 26 [32] wherein said second contact  
2 portion of said solder member including said solder dome is at least one of an array of  
3 solder members on said external surface of said conductive aperture of said second flexible  
4 circuitized substrate.

1           Claim 44. A single chip carrier comprising:

2           a first circuitized substrate having at least one conductive aperture therein having  
3 an external surface;  
4           a second circuitized substrate having at least one conductive aperture therein  
5 having an external surface, said first and second circuitized substrates aligned such that  
6 said at least one conductive aperture of said first circuitized substrate is substantially  
7 aligned with said at least one conductive aperture of said second circuitized substrate, said  
8 at least one conductive aperture of said first circuitized substrate and said at least one  
9 conductive aperture of said second circuitized substrate including a conductive metallic  
10 layer thereon selected from the group consisting of copper, nickel, gold, chromium, solder  
11 and alloys thereof;

12           at least one solder member including a first contact portion for connection to a  
13 printed circuit board extending from said external surface of said conductive aperture of  
14 said first circuitized substrate and a second contact portion extending substantially within  
15 both of said aligned conductive apertures of said first and second circuitized substrates to  
16 said external surface of said conductive aperture of said second circuitized substrate so as  
17 to substantially form a solder dome thereon to secure said circuitized substrates together

18 wherein said second contact portion of said solder member is at least one of an array of  
19 solder members on said external surface of said conductive aperture of said second  
20 circuitized substrate [said metallic material of said at least one conductive aperture of said  
21 first circuitized substrate and said at least one conductive aperture of said second  
22 circuitized substrate including a protective layer thereon, said protective layer selected  
23 from the group consisting of benzatriazole, chlorite, and immersion tin]; and  
24 at least one chip attached to said array of solder members.